The Multinational Power Electronics Association

PSMA

Packaging/Manufacturing Committee

Review Meeting July 23rd , 2026

Jason Rouse, Vikas Gupta, John Bultitude

Co-chairs

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Meeting Minutes

- **APEC 2027 Proposal**
  - Vikas reviewed the status and will recruit Cyntec
  - Doug Hopkins with contact Minje Chen
  - Mike Hayes will recruit a Tyndall presenter
  - Vikas and John B. will prepare a submission by the Deadline of August 14th
  - Draft Presentations Due Jan. 8th, 2027, Final versions for Publication Feb. 9th, 2027
- **Committee Co-Chair Recruitment**
  - Fang Luo offered to co-chair and Vikas will schedule a follow-up meeting
- **3D-PEIM 2026 Update**
  - Please promote this event with your colleagues
  - Please offer any suggestions for a venue in 2027

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APEC 2027 Proposal – Power Packaging for AI

Submission Deadline
August 14th, 2026

Focus on board to core, key points to consider

- **Shift to +/-400V, 800V architecture**
- **Voltage step down strategies for GPU, TPU applications**
- **Solutions (device, packaging) including IBC (Intermediate Bus Converter), VPD (Vertical Power Delivery), IVR (Integrated Voltage Regulator)**

Presentation Subject	Presenter (Affiliation)
Power Delivery Problem Statement – Industry View	**TBD (Hyperscaler)**
Power Delivery Problem Statement – Academia View	**Minjie Chen (Princeton)**, M. Swaminathan (Penn State)
Market Analysis	**Hassan Cheaito (Yole) – *Invitation Sent***
Module Solutions	**TBD (Vicor)**, TBD (Cyntec)
Component Solutions	**TBD (Start-up),** TBD (Monolithic Power)
Innovations	**Noah Sturcken (Ferric)**, Sabin Eftimie (EPIC)
Passives, Materials	**TBD (Tyndall)**, TBD (Materials Company)

Have verbal confirmation from one start-up, second one in internal discussion. These two could cover the module and component slots.

Confirmed speakers in Green font

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Committee Co-Chair Recruitment

Event	Primary PSMA Organizing Committee	PSMA Pkg Chair Responsibility
Committee Role	- PSMA Packaging Committee	**- Chairs committee meetings, set dates, align on agenda** **- Prepare presentation for board meetings** **- Provide brief report** - Solicit special project proposals (e.g. Tech Reports, Roadmaps, etc.)
APEC Session	- PSMA Packaging Committee - Annual event (one pkg session)	**- Lead session proposal, recruit APEC speakers** **- Schedule and chairs review session** **- Communicate with speakers on schedule** **- Provide feedback to speakers** - Co-chairs the session **- Primary contact with APEC, schedules, documentation, etc.** **- Host and drive PSMA packaging meeting at APEC**
3D PEIM	- Highest priority of 3D PEIM, PwrSoC, iWIPP; funded by PSMA - Brian N, Doug Hopkins & Pat McClusky initiate from pkg (steering committee) - Every year (Doug's preference) - Brian N is Treasurer	**- Present a proposal to the board** **- Attends Organizing Committee Meeting** **- Potentially a committee member**
PwrSoC	- Trefon L (Treasurer) is the primary contact, Brian N. on steering committee - Every other year (2027)	**- Attends Organizing Committee Meeting** **- Potentially a committee member**
iWIPP (https://iwipp.org/)	- Andy Lemmon primary contact. Steering committee chair Francesco Iannuzzo - Every other year (Feb 28- Mar 4, 2027; Fukuoka, Japan) - Brian N phase out to Jason R	**- Present a proposal to the board** **- Attends Organizing Committee Meeting** **- Potentially a committee member**

- Color coding under “PSMA Pkg Chair Responsibility” is initial proposal to share responsibilities between 3 co-chairs.
- Should we rotate responsibilities between co-chairs every year?

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Co-Chair Responsibilities

Co-chair 1

- Chairs committee meetings, set dates, align on agenda
- PTR and Solicit special project proposals (e.g. Tech Reports, Roadmaps, etc.)
- iWiPP
  - Present a proposal to the board
  - Attends Organizing Committee Meeting
  - Potentially a committee member

Co-chair 2

- Identify Webinar speakers
- APEC
  - Lead session proposal, recruit APEC speakers
  - Schedule and chairs review session
  - Primary contact with APEC, schedules, documentation, etc.
  - Host and drive PSMA packaging meeting at APEC
- PwrSOC
  - Attends Organizing Committee Meeting
  - Potentially a committee member

Co-chair 3

- Board Meetings
  - Prepare presentation for board meetings
  - Provide brief report
- 3DPEIM
  - Present a proposal to the board
  - Attends Organizing Committee Meeting
  - Potentially a committee member
- APEC
  - Communicate with speakers on schedule
  - Provide feedback to speakers

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3D-PEIM

3D Power Electronics Integration and Man

John Bultitude (johnbultitude101@outlook.com) is signed in

Home | Program | Committee | Call for Papers | Registration | Housing & Travel | Venue | 2026 3D-PEIM: Lab Tours | Sponsors, Exhibitors & Partners | Contact | Previous years

The Sixth International Symposium on 3D Power Electronics Integration & Manufacturing (3D-PEIM)

Tempe, AZ, USA
November 16-19, 2026

Join us for the 2026 3D-PEIM Symposium
Hosted by the Arizona State University (ASU)

Register for 3D-PEIM beginning June 8, 2026.

- **Registration Open https://www.3d-peim.org/**
- **Earlybird discount through September 30th**

https://www.3d-peim.org/

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Local Organization

Chris Bailey
General Chair

Chanyeop Park
Technical Program Chair

Hongbin Yu
Partner & Exhibitor Chair

Leslie Hwang
Publicity Chair

Robina Syed
Site coordinator – Planning, Logistics,
Site, registration

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Organizing Committee

Chris Bailey - General Chair - ASU
Chanyeop Park -Technical Program Co-Chair – ASU
Matt Wilkowski – Technical Program Co-Chair - PSMA
Brian Narveson - Finance Chair - PSMA
Hongbin Yu - Partner/Exhibitor Chair – ASU
Doug Hopkins - Publications Chair
Leslie Hwang - Publicity Chair – ASU
Web Master & Registration Site – Lisa Horzepa - Consultant
Ruby - Site coordinator, Planning, Logistics, Site, Registration- ASU
Vikas Gupta – Packaging Committee Co-Chairman - PSMA

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Program

Program at a Glance

Session	Chairs
Advanced Packaging & 3D Integrated Modules	Raja Ayyanar, Arizona State University; Hongbin Yu, Arizona State University
Materials for Advanced Packaging	Chanyeop Park, Arizona State University; Adam Morgan, NoMIS Power
Thermal Management	Jong Ryu, North Carolina State University
Design, Modeling & Simulation	Doug Hopkins, North Carolina State University; Leslie Hwang, Arizona State University
Reliability & Failure Analysis	Jeff Ewanchuk, RTRC
Passive Components	Trifon Liakopoulos, Eneira; Kousuke Miyaji, Shinshu University
Power Delivery & Energy Storage	Francesco Carobolante, IoTissimo
Partner Session	Hongbin Yu, Arizona State University; Brian Narveson, PSMA
MTW Lab Tours (separate registration required)	Multiple ASU Researchers

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Free Tutorials Monday

The 3D-PEIM Organizing Committee is pleased to announce the addition of four two-hour short tutorials to the 3D-PEIM conference program.

The Tutorials will take place on **Monday afternoon, November 16**. There will be 2 sessions and 2 tracks each session:

1 PM – 3 PM:

-Advanced Packaging
George Dogiamis (DECA), Chanyeop Park (ASU), Hongbin Yu (ASU), and Chris Bailey (ASU)

-Trends in Magnetic Material Properties to Meet the Challenges of Supporting High-Performance Computing
Matt Wilkowski (Wurth Elektronik)

3 PM – 3:15 PM Coffee break

3:15 PM – 5:15 PM

-Die-Attach by Metal Powder Sintering: The Science and Practice
G.Q. Lu (Virginia Tech)

-Digital Twin-Driven Reliability and Prognostics in Power Electronics Systems
Jong Eun Ryu (North Carolina State University)

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Free Panel Session Monday

Following the tutorials, there will be panel session on “**Key Challenges for 3D Power Electronics Packaging/Manufacturing**” on November 16 (Monday) 5:30 PM – 7:00 PM from academic and industry experts (tentatively confirmed):

- **Ravi Mahajan**, Intel/HIR Chair
- **Doug Hopkins**, North Carolina State University/HIR Power Chapter
- **Chris Bailey**, Arizona State University/HIR Modeling and Simulation Chapter
- **Pat McCluskey**, University of Maryland/HIR Thermal Chapter
- **George Dogiamis**, Deca Technologies
- **Francesco Carobolante**, IoTissimo

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Venue

Venue

The 2026 3D-PEIM conference will be held at the **ASU Skysong Building 3 (Synergy I & II Rooms)**, located at 1365 N. Scottsdale Rd., Scottsdale, AZ 85257.

SkySong, the ASU Scottsdale Innovation Center, is home to a thriving business community that links technology, research, education and entrepreneurship to position ASU and greater Phoenix as global leaders in the knowledge economy. SkySong is a 1.2 million-square-foot mixed-use development located on a 42-acre campus in Scottsdale, Arizona. With 15 options between two buildings, SkySong has a range of spaces and features to bring your meetings and events to life.

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ASU Campus

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Gala Dinner – Botanical Gardens (Wednesday Evening)

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Thank You

Next Committee Meeting

Thursday August 13th 10:00am central time

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